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 TI High-strength **solder** alloy  
 IN Kawaguchi, Toranosuke; Hayashi, Takayuki  
 PA Nihon Almit Co., Ltd., Japan  
 SO PCT Int. Appl., 11 pp.  
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 DT Patent  
 LA Japanese  
 FAN.CNT 1

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	JP 10235491	A2	19980908	JP 1994-154244	19940613
	JP 3045453	B2	20000529		
	CA 2162263	AA	19951214	CA 1995-2162263	19950323
	AU 9520825	A1	19960105	AU 1995-20825	19950323
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	EP 748666	B1	19991020		
	R: DE, FR, GB, NL, SE				
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	FI 9600630	A	19960212	FI 1996-630	19960212
PRAI	JP 1994-154244	A	19940613		
	WO 1995-JP531	W	19950323		
AB	<b>Solder</b> alloys having higher mech. strengths and excellent wettability, comprise Si 0.0005-0.35, <b>Ag</b> 0-5.0, <b>Sb</b> 0-10.0, <b>Bi</b> 0-10.0, <b>Sn</b> 20-95, <b>Pb</b> 0-70, and <b>Ca</b> 0-0.5%.				